SPECION, s.r.o.
LABORATORNÍ A ZKUŠEBNÍ TECHNIKA

CEITEC NANO

Leica
MICROSYSTEMS

Material samples preparation workshop in Brno, focused on ion beam milling system and mechanical target preparation.

29. - 30. 3. 2017, CEITEC Nano Research Infrastructure, Brno University of Technology,
Purkyňova 123, 612 00 Brno, Czech Republic

Presenting instruments: Leica EM TIC3X, Ion Beam Milling System (web)
Leica EM TXP, Mechanical Target Preparation Device (web)

Registration: bacik@specion.biz

Program:

Wednesday 29.3.:

10:00 – 10:15	Welcome & introducing the agenda
10:15 – 11:15	Lecture: Ion beam slope cutting / cross sectioning and surface preparation – Leica EM TIC 3X (Wolfgang Grünewald, Leica Microsystems)
11.15 – 11:30	Coffee break
11:30 – 12.15	Lecture: Mechanical sample preparation / target preparation with the Leica EM TXP (Wolfgang Grünewald, Leica Microsystems)
12:15 – 13:15	Lunch
13:15 – 13:45	Lecture: CEITEC (Ondřej Man, CEITEC Nano)
13:45 – 14:45	Group Green: Demonstration of the Leica EM TXP - mechanical sample preparation / target preparation instrument. (Martin Bačík, Specion)
13:45 – 14:45	Group Red: Demonstration of the Leica EM TIC 3X – slope cutting / cross sectioning and surface preparation device. (Wolfgang Grünewald, Leica Microsystems)
14:45 – 15:00	Coffee break
15:00 – 16:00	Group Red: Demonstration of the Leica EM TXP - mechanical sample preparation / target preparation instrument. (Martin Bačík, Specion)
15:00 – 16:00	Group Green: Demonstration of the Leica EM TIC 3X – slope cutting / cross sectioning and surface preparation device. (Wolfgang Grünewald, Leica Microsystems)

16:00 – 16:30 All: Loading a sample into the Leica EM TIC3X and starting ion beam slope cut / cross sectioning process for an overnight run

16:30 – 17:00 Q&A, closing of day one.

Thursday 30.3.:

09:30 – 09:45 Welcome and answering any open questions from day one.

09:45 – 10:30 Lecture: Ion beam sample preparation for TEM and SEM – Leica EM RES102 (Wolfgang Grünewald, Leica Microsystems)

10.30 – 10:45 Coffee break

10:45 – 12:15 SEM Imaging of the sample from the first day and discussions (Ondrej Man & Wolfgang Grünewald)

12:15 – 13:15 Lunch

13:15 – 14:45 Discussion on Leica EM TXP and TEM lamella preparation (Wolfgang Grünewald & Martin Bacik)

15:00 Q&A, closing the workshop.